



Material Content Data Sheet



Sales Product Name		IPB037N06N3 G		Issued		29. August 2013			
MA#		MA000398196							
Package		PG-TO263-3-2		Weight*		1464.19 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	5.184	0.35	0.35	3541	3541	
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		582		
	inorganic material	phosphorus	7723-14-0	0.256	0.02		175		
	non noble metal	copper	7440-50-8	851.691	58.15	58.23	581680	582437	
wire	non noble metal	aluminium	7429-90-5	8.302	0.57	0.57	5670	5670	
encapsulation	organic material	carbon black	1333-86-4	8.761	0.60		5983		
	plastics	epoxy resin	-	96.368	6.58		65816		
	inorganic material	silicondioxide	60676-86-0	478.918	32.71	39.89	327087	398886	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6595	6595	
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156	
solder	noble metal	silver	7440-22-4	0.099	0.01		68		
	non noble metal	tin	7440-31-5	0.080	0.01		54		
	non noble metal	lead	7439-92-1	3.796	0.26	0.28	2593	2715	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

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